



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-01-10
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STB6N80K5	TLD2*VJ8GB52	A	3068	2017-01-10
	Amount	UoM	Unit type	ST ECOPACK Grade
	1380.00	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	10.2-9.15-4.5	2	gull wing	
Comment	D2PAK			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	TLD2*VJ8GB52					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	5.398	mg	supplier	die	Silicon (Si)	7440-21-3		5.140	mg	952213	3725
				supplier	metallization	Aluminium (Al)	7429-90-5		0.096	mg	17781	70
				supplier	metallization	Copper (Cu)	7440-50-8		0.035	mg	6483	25
				supplier	Passivation	Silicon Nitride	12033-89-5		0.022	mg	4074	16
				supplier	Passivation	Silicon Oxide	7631-86-9		0.055	mg	10187	40
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.003	mg	556	2
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.035	mg	6483	25
Leadframe	Copper & its alloys	778.632	mg	supplier	alloy	Silver (Ag)	7440-22-4		0.012	mg	2223	9
				supplier	alloy	Copper (Cu)	7440-50-8		777.537	mg	998594	563433
				supplier	alloy	Iron (Fe)	7439-89-6		0.358	mg	460	259
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.654	mg	840	474
				supplier	metallization	Nickel (Ni)	7440-02-0		0.077	mg	98	56
Soft solder	Solder	5.012	mg	JIG - R	solder	Phosphorus (P)	12185-10-3		0.006	mg	8	4
				supplier	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	4.787	mg	955108	3469
				supplier	solder	Silver (Ag)	7440-22-4		0.125	mg	24940	90
				supplier	solder	Tin (Sn)	7440-31-5		0.100	mg	19952	72
Bonding wires	Other inorganic materials	0.774	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.771	mg	996124	559
				supplier	wire	Magnesium (Mg)	7439-95-4		0.003	mg	3876	2
Encapsulation	Other Organic Materials	587.695	mg	supplier	mold compound	Silica, vitreous	60676-86-0		514.232	mg	874998	372632
				supplier	mold compound	Tetramethyl-biphenyl-diy-bis oxymethylene-bi	EC 413-900-7		23.508	mg	40000	17035
				supplier	mold compound	Epoxy Resin	25068-38-6		17.631	mg	30000	12776
				supplier	mold compound	phenol resin	29690-82-2		29.385	mg	50000	21293
				supplier	mold compound	Carbon black	1333-86-4		2.939	mg	5002	2130
Connections coating	Solder	2.489	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		2.489	mg	1000000	1804